CyberOptics Announces New ReticleSense® Airborne Particle Sensor Quartz

Quartz Housing Designed to be Compatible with ASML, Nikon and Canon Scanners in Semiconductor Fabs

Seoul, Korea – SEMICON Korea — Jan. 29, 2015— CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will announce its new addition to the ReticleSense™ wireless measurement portfolio at SEMICON Korea in Booth #1857 at COEX, from Feb. 4 – 6, 2015. The new ReticleSense Airborne Particle Sensor Quartz (APSRQ) has a quartz housing for use in semiconductor tools that handle quartz reticles. The technology inside is the same CyberOptics particle sensor technology widely used by equipment OEMs and fabs worldwide that improves yields and tool uptime.

Designed and developed specifically for use with scanners in the semiconductor fabs, the ReticleSense APSRQ has all of the necessary alignment marks and bar codes for compatibility with ASML, Nikon and Canon scanners. The APSRQ can be loaded directly into a scanner just like a quartz reticle and travel the entire reticle path to detect in real-time when and where particles occur.

“Quickly identifying the source of the contamination is challenging with traditional surface scan reticles, in-situ or hand-held methods. In addition, these methods lack real-time feedback, and often unexpected particle sources go undetected or take a long time to finally identify. The APSRQ enables quick particle qualification in reticle environments. APSRQ technology saves the time-consuming task of partitioning with multiple surface scan reticles which require the high-value scanner to be brought off-line for lengthy particle source troubleshooting,” said Ferris Chen, Director of Global Sales, CyberOptics. “By extending the line to include a quartz airborne particle sensor, we’re helping our customers exceed manufacturing quality and productivity standards in the Photo Lithography scanner environment.”

WaferSense® and ReticleSense Airborne Particle Sensors enable equipment engineers to shorten equipment qualification, release to production and maintenance cycles, all while reducing expenses. Customers have experienced up to 88% time savings, up to 95% reduction in costs, and up to 20X the through-put with half the manpower resource requirements using the WaferSense or ReticleSense sensors relative to legacy surface scan wafer methods.

About the WaferSense and ReticleSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS) and the Airborne Particle Sensor (APS) are available now in 200mm, 300mm and 450mm wafer sizes. Additionally, both APS and ALS are available in 150mm sizes. The ReticleSense Airborne Particle Sensor (APSR), the ReticleSense Auto Leveling System (ALSR) and the new ReticleSense Airborne Particle Sensor Quartz (APSRQ) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company’s website at www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the level of revenue and loss we record in 2014; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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